

L Number	Hits	Search Text	DB	Time stamp
1	1	356/399,400.ccls. and laser and (notch or hole or fiducial) and (wafer or semiconductor) and @pd>20040112	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 17:07
2	23	356/237.1,237.2-237.5.ccls. and laser and (notch or hole or fiducial) and (wafer or semiconductor) and @pd>20030821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 17:11
3	9	356/630-632,426,504.ccls. and laser and (notch or hole or fiducial) and (wafer or semiconductor) and @pd>20030821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 17:10
4	5	324/229,230.ccls. and laser and (notch or hole or fiducial) and (wafer or semiconductor) and @pd>20030821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 17:10
5	0	427/9,10.ccls. and laser and (notch or hole or fiducial) and (wafer or semiconductor) and @pd>20030821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 17:10
6	1	250/231.14-231.17.ccls. and laser and (notch or hole or fiducial) and (wafer or semiconductor) and @pd>20030821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 17:11
7	35	356/614.ccls. and laser and (notch or hole or fiducial) and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/03 17:12